

DESCRIPTION

Title of Invention

RESIN COMPOSITION, LAMINATE SHEET, AND MULTILAYER
PRINTED WIRING BOARD

5 Technical Field

[0001] The present invention relates to a resin composition, a laminate
and a multilayer printed wiring board.

Background Art

10 [0002] In mobile communication devices represented by cell phones,
base station apparatuses thereof, network infrastructure devices such as
severs and routers, and electronic devices such as large computers,
signals used are being increased year by year in the speed and the
capacity. Along therewith, readiness for higher frequencies becomes
15 necessary for printed wiring boards mounted on these electronic devices,
and there are demanded substrate materials having a low relative
dielectric constant and a low dielectric loss tangent which enable the
transmission loss to be reduced. In recent years, as such applications
handling high-frequency signals, besides in the above-mentioned
20 electronic devices, also in ITS fields (automobiles, traffic system fields)
and indoor short-distance communication fields, there have advanced the
practical uses and practical plans of novel systems handling high-
frequency radio signals; and it is supposed that hereafter, low-
transmission loss substrate materials are further demanded on printed
wiring boards mounted on these devices.

25 [0003] Further since from recent year's environmental problems, there
have been demanded the mounting of electronic components by using a

lead-free solder, and the flame retardation by the halogen freeness, there become necessary a higher heat resistance and flame retardancy for materials for printed wiring board than hitherto.

[0004] For printed wiring boards demanding a low transmission loss, as heat-resistant thermoplastic polymers exhibiting excellent high-frequency characteristics, polyphenylene ether (PPE)-based resins are conventionally used. In uses of polyphenylene ether-based resins, there are proposed, for example, methods of using a polyphenylene ether and a thermosetting resin in combination; and specifically, there are disclosed a resin composition containing a polyphenylene ether and an epoxy resin (for example, see Patent Literature 1), a resin composition using a polyphenylene ether and a cyanate ester resin, which is low in the relative dielectric constant among thermosetting resins, in combination (for example, see Patent Literature 2), and the like.

[0005] Further the present inventors propose a resin composition capable of being improved in compatibility, heat resistance, thermal expansion characteristics, adhesiveness to conductors and the like by using a polyphenylene ether resin and a polybutadiene resin as bases and making the resin composition to have a semi-IPN structure in its production stage (A-stage) (for example, see Patent Literature 3).

[0006] Further, use of maleimide compounds as a material for printed wiring boards is being studied. For example, Patent Literature 4 discloses a resin composition which has a maleimide compound having at least two maleimide skeletons, an aromatic diamine compound having at least two amino groups and having an aromatic ring structure, a catalyst having a basic group and a phenolic hydroxyl group and promoting the

reaction of the maleimide compound with the aromatic diamine compound, and a silica.

Citation List

Patent Literature

- 5 [0007] Patent Literature 1: JP 58-69046 A1
Patent Literature 2: JP 61-18937 A1
Patent Literature 3: JP 2008-95061 A1
Patent Literature 4: JP 2012-255059 A1

Summary of Invention

Technical Problem

10 [0008] For substrate materials for printed wiring boards to be used in the recent year's high-frequency band, however, it is demanded that, in addition to the high-frequency characteristics and high adhesiveness to conductors, various types of characteristics such as low thermal
15 expansion coefficient be further excellent,.

[0009] The present invention, in consideration of such a present situation, has an object to provide a resin composition having excellent high-frequency characteristics (low relative dielectric constant, low dielectric loss tangent), and having also the low thermal expansion
20 characteristics and the adhesiveness to conductors in high levels, and a laminate and a multilayer printed wiring board which are produced by using the resin composition and are good in appearance and handleability.

Solution to Problem

[0010] As a result of exhaustive studies to solve the above problems, the
25 present inventors have found that a resin composition comprising a compound having a specific structure and a thermoplastic resin can solve

the above problems, and this finding has led to the completion of the present invention.

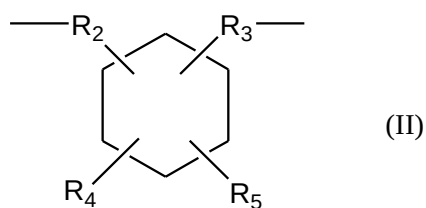
[0011] That is, the present invention includes the following aspects.

[1] A resin composition comprising an (A) maleimide compound having a saturated or unsaturated divalent hydrocarbon group, and a thermoplastic resin.

[2] The resin composition according to [1], wherein the number of carbon atoms of the hydrocarbon group is 8 to 100.

[3] The resin composition according to [1] or [2], wherein the hydrocarbon group is a group represented by the following formula (II).

[0012] [Chemical Formula 1]

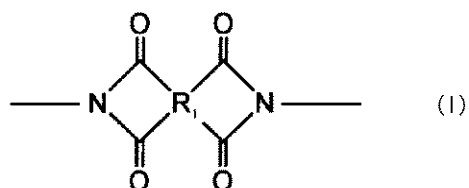


In the formula (II), R₂ and R₃ each independently represent an alkylene group having 4 to 50 carbon atoms; R₄ represents an alkyl group having 4 to 50 carbon atoms; and R₅ represents an alkyl group having 2 to 50 carbon atoms.

[0013] [4] The resin composition according to any one of [1] to [3], wherein the (A) maleimide compound having a saturated or unsaturated divalent hydrocarbon group further has a divalent group having at least two imido bonds.

[5] The resin composition according to [4], wherein the divalent group having at least two imido bonds is a group represented by the following formula (I).

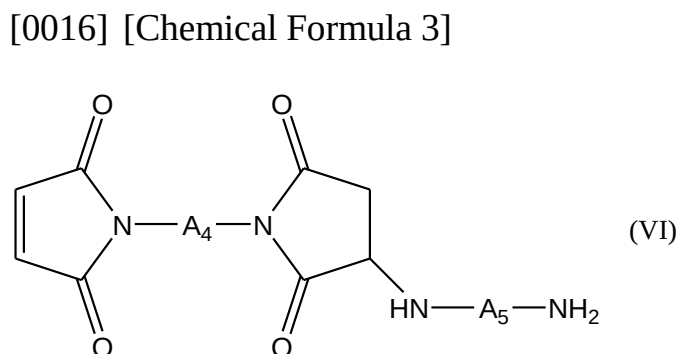
[0014] [Chemical Formula 2]



In the formula (I), R₁ represents a tetravalent organic group.

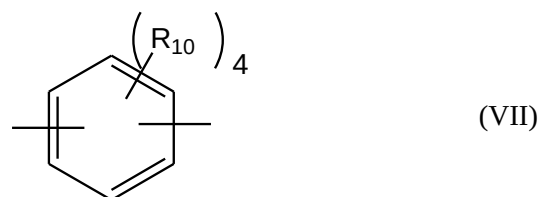
[0015] [6] The resin composition according to any one of [1] to [5], further comprising a (B) aromatic maleimide compound having a structure having a maleimido group bonded to an aromatic ring.

[7] The resin composition according to [6], wherein the (B) aromatic maleimide compound is a compound represented by the following formula (VI).



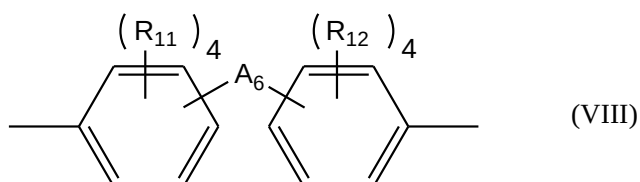
In the formula (VI), A₄ represents a residue represented by the following formula (VII), (VIII), (IX) or (X); and A₅ represents a residue represented by the following formula (XI).

[0017] [Chemical Formula 4]



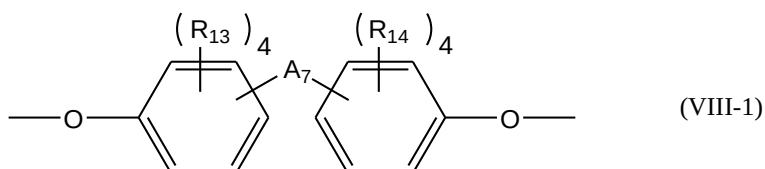
In the formula (VII), R₁₀ each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom.

[0018] [Chemical Formula 5]



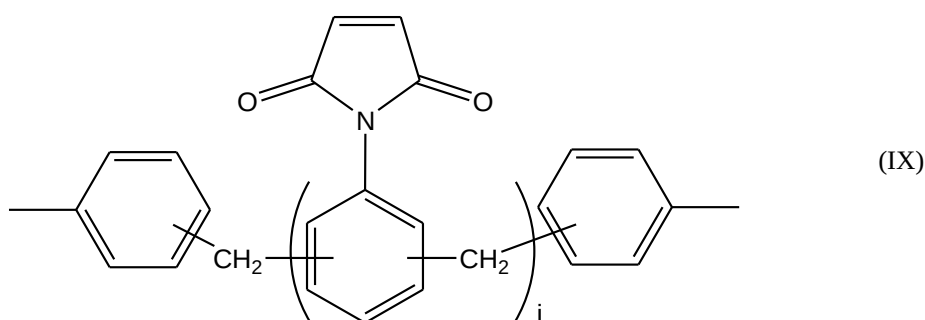
In the formula (VIII), R₁₁ and R₁₂ each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom; and A₆ represents an alkylene group or an alkylidene group having 1 to 5 carbon atoms, an ether group, a sulfide group, a sulfonyl group, a carbonyl group, a single bond or a residue represented by the following formula (VIII-1).

[0019] [Chemical Formula 6]



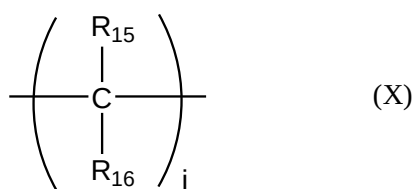
In the formula (VIII-1), R₁₃ and R₁₄ each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom; and A₇ represents an alkylene group having 1 to 5 carbon atoms, an isopropylidene group, an ether group, a sulfide group, a sulfonyl group, a carbonyl group or a single bond.

[0020] [Chemical Formula 7]



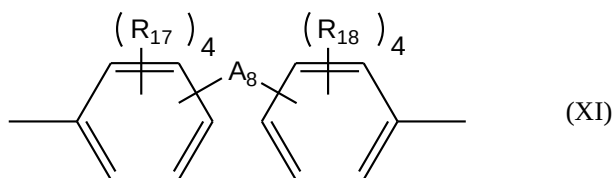
In the formula (IX), i is an integer of 1 to 10.

[0021] [Chemical Formula 8]



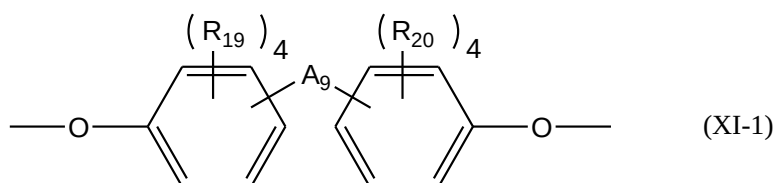
- 5 In the formula (X), R₁₅ and R₁₆ each independently represent a hydrogen atom or an aliphatic hydrocarbon group having 1 to 5 carbon atoms; and j is an integer of 1 to 8.

[0022] [Chemical Formula 9]



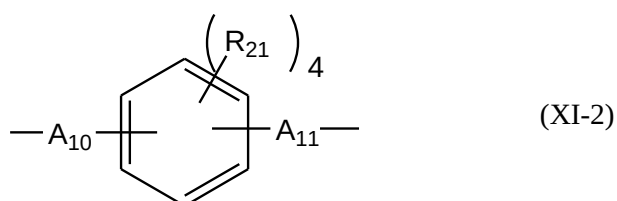
- 10 In the formula (XI), R₁₇ and R₁₈ each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an alkoxy group having 1 to 5 carbon atoms, a hydroxyl group or a halogen atom; and A₈ represents an alkylene group or an alkylidene group having 1 to 5 carbon atoms, an ether group, a sulfide group, a sulfonyl group, a carbonyl group, a fluorenylene group, a single bond, a residue represented by the following formula (XI-1) or a residue represented by the following formula (XI-2).
- 15

[0023] [Chemical Formula 10]



In the formula (XI-1), R₁₉ and R₂₀ each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom; and A₉ represents an alkylene group having 1 to 5 carbon atoms, an isopropylidene group, a m-phenylenediisopropylidene group, a p-phenylenediisopropylidene group, an ether group, a sulfide group, a sulfonyl group, a carbonyl group or a single bond.

[0024] [Chemical Formula 11]



In the formula (XI-2), R₂₁ each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom; and A₁₀ and A₁₁ each independently represent an alkylene group having 1 to 5 carbon atoms, an isopropylidene group, an ether group, a sulfide group, a sulfonyl group, a carbonyl group or a single bond.

[0025] [8] The resin composition according to any one of [1] to [7], wherein a weight-average molecular weight of the (A) maleimide compound having a saturated or unsaturated divalent hydrocarbon group is 500 to 10000.

[9] A laminate comprising a resin layer comprising a cured substance of

the resin composition according to any one of [1] to [8], and a conductor layer.

[10] A multilayer printed wiring board comprising a resin layer comprising a cured substance of the resin composition according to any one of [1] to [8], and a circuit layer.

Advantageous Effects of Invention

[0026] The present invention can provide a resin composition having excellent high-frequency characteristics (low relative dielectric constant, low dielectric loss tangent), and having also the low thermal expansion characteristics and the adhesiveness to conductors in high levels, and a laminate and a multilayer printed wiring board which are produced by using the resin composition.

[0027] Further, in conventional resin films, in the case where no reinforcing base materials are blended in their resin compositions, it is likely that the handleability of the resin films becomes worse and the strength cannot also be sufficiently held. By contrast, the resin film fabricated by using the resin composition according to the present invention, even without having a reinforcing base material, can become one excellent in appearance and handleability (tackiness, cracking, powder dropping and the like).

[0028] The laminate and the multilayer printed wiring board according to the present invention, since being formed by using the resin composition of the present invention, have excellent dielectric characteristics of being low in both the relative dielectric constant and the dielectric loss tangent in the high-frequency region.

Brief Description of Drawings

[0029] Figure 1 is a schematic diagram illustrating a production step of a multilayer printed wiring board according to the present embodiment.

Figure 2 is a schematic diagram illustrating a production step of an inner layer circuit board.

Figure 3 is a schematic diagram illustrating a production step of a multilayer printed wiring board according to the present embodiment.

Description of Embodiments

[0030] Hereinafter, a preferred embodiment of the present invention will be described in detail, as required, by reference to the drawings. However, the present invention is not limited to the following embodiment.

[0031] <Definitions>

In the present description, a "high-frequency region" refers to a region of 0.3 GHz to 300 GHz, particularly 3 GHz to 300 GHz. In the present description, a numerical value range indicated by using "to" indicates a range including numerical values described before and after the "to" as the minimum value and the maximum value, respectively. In numerical value ranges described stepwise in the present description, the upper limit value or the lower limit value in a numerical value range of a certain step may be replaced by the upper limit value or the lower limit value of another step. In a numerical value range described in the present description, the upper limit value or the lower limit value in the numerical value range may be replaced by a value indicated in Examples. "A or B" may include either one of A and B, or may include the both.

[0032] [Resin composition]

A resin composition of the present embodiment comprises an (A)

maleimide compound having a saturated or unsaturated divalent hydrocarbon group, and a thermoplastic resin.

[0033] <(A) Maleimide compound having a saturated or unsaturated divalent hydrocarbon group>

5 A maleimide compound having a saturated or unsaturated divalent hydrocarbon group according to the present embodiment is referred to as an (A) component in some cases. The (A) component is a compound having an (a) maleimido group, and a (c) saturated or unsaturated divalent hydrocarbon group. In some cases, the (a)
10 maleimido group is referred to as a structure (a); and the (c) saturated or unsaturated divalent hydrocarbon group is referred to as a structure (c). By using the (A) component, there can be obtained a resin composition having high-frequency characteristics and high adhesiveness to conductors.

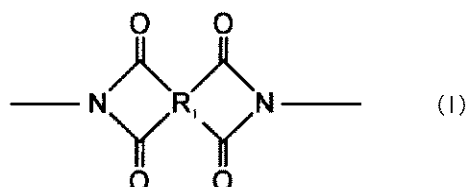
15 [0034] The (A) component may have a (b) divalent group having at least two imido bonds in addition to the structure (a) and the structure (c). The (b) divalent group having at least two imido bonds is referred to as a structure (b) in some cases.

[0035] The (a) maleimido group is not especially limited, and is a
20 common maleimido group. The (a) maleimido group may be bonded to an aromatic ring or an aliphatic chain, but from the viewpoint of dielectric characteristics, it is preferable that the maleimido group be bonded to a long-chain aliphatic chain (for example, a saturated hydrocarbon group having 8 to 100 carbon atoms). By making the (A) component to have
25 a structure in which the (a) maleimido group is boded to a long-chain aliphatic chain, the high-frequency characteristics of the resin

composition can further be improved.

[0036] The structure (b) is not especially limited, but examples thereof include a group represented by the following formula (I).

[0037] [Chemical Formula 12]



[0038] In the formula (I), R_1 represents a tetravalent organic group. R_1 is not especially limited as long as being a tetravalent organic group, but for example, from the viewpoint of the handleability, may be a hydrocarbon group having 1 to 100 carbon atoms, may be a hydrocarbon group having 2 to 50 carbon atoms, or may be a hydrocarbon group having 4 to 30 carbon atoms.

[0039] R_1 may be a substituted or nonsubstituted siloxane site. Examples of the siloxane site include structures originated from dimethylsiloxane, methylphenylsiloxane and diphenylsiloxane.

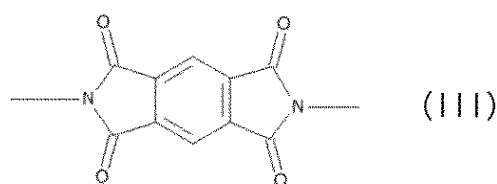
[0040] In the case where R_1 is substituted, examples of the substituent include an alkyl group, an alkenyl group, an alkynyl group, a hydroxyl group, an alkoxy group, a mercapto group, a cycloalkyl group, a substituted cycloalkyl group, a heterocycle group, a substituted heterocycle group, an aryl group, a substituted aryl group, a heteroaryl group, a substituted heteroaryl group, an aryloxy group, a substituted aryloxy group, a halogen atom, a haloalkyl group, a cyano group, a nitro group, a nitroso group, an amino group, an amido group, $-C(O)H$, $-NR_xC(O)-N(R_x)_2$, $-OC(O)-N(R_x)_2$, an acyl group, an oxyacyl group, a

carboxyl group, a carbamate group and a sulfonamido group. Here, R_x represents a hydrogen atom or an alkyl group. One or two or more of these substituents can be selected according to the purposes, the applications and the like.

5 [0041] As R_1 , preferable is, for example, a tetravalent residue of an acid anhydride having two or more anhydride rings in one molecule thereof, that is, a tetravalent group made by eliminating two acid anhydride groups ($-\text{C}(=\text{O})\text{OC}(=\text{O})-$) from the acid anhydride. Examples of the acid anhydride include compounds as described later.

10 [0042] From the viewpoint of the mechanical strength, it is preferable that R_1 be aromatic, and it is more preferable that R_1 be a group made by eliminating two acid anhydride groups from pyromellitic anhydride. That is, it is more preferable that the structure (b) be a group represented by the following formula (III).

15 [0043] [Chemical Formula 13]

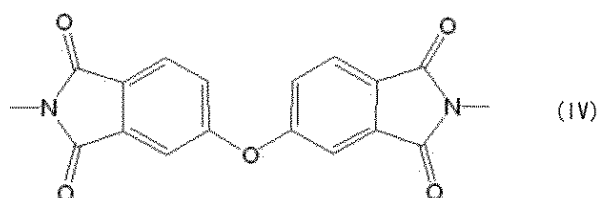


[0044] From the viewpoint of the flowability and the circuit embeddability, it is preferable that the structure (b) be present in plural numbers in the (A) component. In this case, the structures (b) may be identical or may be different. It is preferable that the number of the structures (b) in the (A) component be 2 to 40; being 2 to 20 is more preferable; and being 2 to 10 is still more preferable.

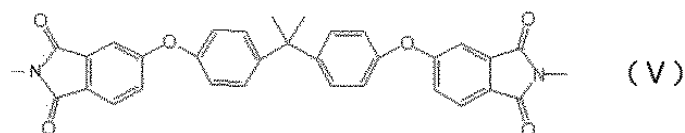
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[0045] From the viewpoint of the dielectric characteristics, the structure (b) may be a group represented by the following formula (IV) or the following formula (V).

[0046] [Chemical Formula 14]



[0047] [Chemical Formula 15]



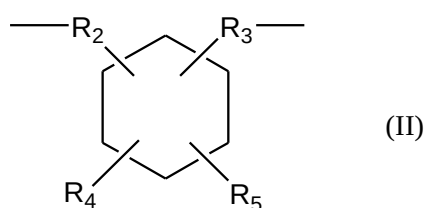
[0048] The structure (c) is not especially limited, and may be any of linear, branched or cyclic. From the viewpoint of high-frequency characteristics, it is preferable that the structure (c) be an aliphatic hydrocarbon group. Then, the number of carbon atoms of the saturated or unsaturated divalent hydrocarbon group may be 8 to 100, or may be 10 to 70 or 15 to 50. The hydrocarbon group may have a branch. It is preferable that the structure (c) be an alkylene group having 8 to 100 carbon atoms which may have a branch; being an alkylene group having 10 to 70 carbon atoms which may have a branch is more preferable; and being an alkylene group having 15 to 50 carbon atoms which may have a branch is still more preferable. When the structure (c) is an alkylene group having 8 or more carbon atoms which may have a branch, the molecular structure is easily made to be of a three-dimensional one, and the density is easily lowered due to the increase in the free volume of the

polymer. That is, since a low dielectric constant can be attained, it becomes easy for the high-frequency characteristics of the resin composition to be improved. When the (A) component has the structure (c), the flexibility of the resin composition according to the present embodiment is improved, and the handleability (tackiness, cracking, powder dropping and the like) and the strength of a resin film fabricated from the resin composition can be enhanced.

[0049] Examples of the structure (c) include alkylene groups such as a nonylene group, a decylene group, an undecylene group, a dodecylene group, a tetradecylene group, a hexadecylene group, an octadecylene group and a nonadecylene group; arylene groups such as a benzylene group, a phenylene group and a naphthylene group; arylene alkylene groups such as a phenylene methylene group, a phenylene ethylene group, a benzylpropylene group, a naphthylene methylene group and a naphthylene ethylene group; and arylene dialkylene groups such as a phenylene dimethylene group and a phenylene diethylene group.

[0050] From the viewpoint of the high-frequency characteristics, the low-thermal expansion characteristics, the adhesiveness to conductors, the heat resistance and the low hygroscopic property, as the structure (c), the group represented by the following formula (II) is especially preferable.

[0051] [Chemical Formula 16]



[0052] In the formula (II), R₂ and R₃ each independently represent an alkylene group having 4 to 50 carbon atoms. From the viewpoint of the further improvement of the flexibility and the easiness of the synthesis, it is preferable that R₂ and R₃ each independently be an alkylene group having 5 to 25 carbon atoms; being an alkylene group having 6 to 10 carbon atoms is more preferable; and being an alkylene group having 7 to 10 carbon atoms is still more preferable.

[0053] In the formula (II), R₄ represents an alkyl group having 4 to 50 carbon atoms. From the viewpoint of the further improvement of the flexibility and the easiness of the synthesis, it is preferable that R₄ be an alkyl group having 5 to 25 carbon atoms; being an alkyl group having 6 to 10 carbon atoms is more preferable; and being an alkyl group having 7 to 10 carbon atoms is still more preferable.

[0054] In the formula (II), R₅ represents an alkyl group having 2 to 50 carbon atoms. From the viewpoint of the further improvement of the flexibility and the easiness of the synthesis, it is preferable that R₅ be an alkyl group having 3 to 25 carbon atoms; being an alkyl group having 4 to 10 carbon atoms is more preferable; and being an alkyl group having 5 to 8 carbon atoms is still more preferable.

[0055] From the viewpoint of the flowability and the circuit embeddability, the structure (c) may be present in plural numbers in the (A) component. In this case, the structures (c) may be identical or may be different. For example, it is preferable that 2 to 40 structures (c) be present in the (A) component; the presence of 2 to 20 structures (c) is more preferable; and the presence of 2 to 10 structures (c) is still more preferable.

[0056] The content of the (A) component in the resin composition is not especially limited. From the viewpoint of the heat resistance, it is preferable that the content of the (A) component be 2 to 98% by mass to the total mass of the resin composition (solid content); being 10 to 50% by mass is more preferable; and being 10 to 30% by mass is still more preferable.

[0057] The molecular weight of the (A) component is not especially limited. From the viewpoint of the handleability, the flowability and the circuit embeddability, it is preferable that the weight-average molecular weight (Mw) of the (A) component be 500 to 10000; being 1000 to 9000 is more preferable; being 1500 to 9000 is still more preferable; being 1500 to 7000 is further still more preferable; and being 1700 to 5000 is especially preferable.

[0058] Mw of the (A) component can be measured by a gel permeation chromatography (GPC) method.

[0059] Here, the measurement condition of GPC is as follows.

Pump: L-6200 type [manufactured by Hitachi High-Technologies Corp.]

Detector: L-3300 type RI [manufactured by Hitachi High-Technologies Corp.]

Column oven: L-655A-52 [manufactured by Hitachi High-Technologies Corp.]

Guard column and columns: TSK Guardcolumn HHR-L + TSKgel G4000HHR + TSKgel G2000HHR [all, manufactured by Tosoh Corp., trade name]

Column size: 6.0 × 40 mm (guard column), 7.8 × 300 mm

(columns)

Eluent: tetrahydrofuran

Specimen concentration: 30 mg/5 mL

Injection volume: 20 μ L

5 Flow volume: 1.00 mL/min

Measurement temperature: 40°C

[0060] A method for producing the (A) component is not limited. The (A) component may be fabricated, for example, by reacting an acid anhydride with a diamine to thereby synthesize an amine-terminated compound, and thereafter reacting the amine-terminated compound with an excessive amount of maleic anhydride.

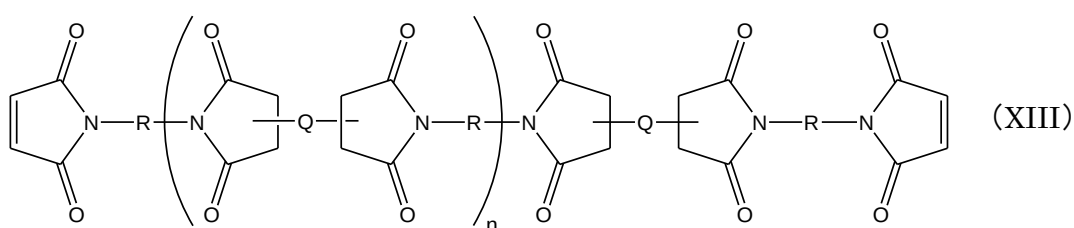
[0061] Examples of the acid anhydride include pyromellitic anhydride, maleic anhydride, succinic anhydride, 3,3',4,4'-benzophenonetetracarboxylic dianhydride, 3,3',4,4'-biphenyltetracarboxylic dianhydride and 3,3',4,4'-diphenylsulfonetetracarboxylic dianhydride. These acid anhydrides may be used singly or in combinations of two or more according to the purposes, applications and the like. Here, as described above, As R_1 of the above formula (I), there can be used tetravalent organic groups originated from acid anhydrides as cited in the above. From the viewpoint of better dielectric characteristics, it is preferable that the acid anhydride be pyromellitic anhydride.

[0062] Examples of the diamine include dimer diamines, 2,2-bis(4-(4-aminophenoxy)phenyl)propane, 1,3-bis(4-aminophenoxy)benzene, 4,4'-bis(4-aminophenoxy)biphenyl, 4,4'-diamino-3,3'-dihydroxybiphenyl, 1,3-bis[(2-(4-aminophenyl)-2-propyl]benzene, 1,4-bis[(2-(4-

aminophenyl)-2-propyl]benzene, polyoxyalkylenediamines, and [3,4-bis(1-aminoheptyl)-6-hexyl-5-(1-octenyl)]cyclohexene. These may be used singly or in combinations of two or more according to the purposes, applications and the like.

5 [0063] The (A) component may be, for example, a compound represented by the following formula (XIII).

[Chemical Formula 17]



10 [0064] In the formula, R and Q each independently represent a divalent organic group. As R, a group having the same structure as the above-mentioned structure (c) can be used, and as Q, the same group as the above-mentioned R₁ can be used. n represents an integer of 1 to 10.

[0065] As the (A) component, commercially available compounds can also be used. Examples of commercially available compounds include products manufactured by Designer Molecules Inc., and specifically include BMI-1500, BMI-1700, BMI-3000, BMI-5000 and BMI-9000 (any of which is a trade name). From the viewpoint of acquiring better high-frequency characteristics, it is more preferable that as the (A) component, BMI-3000 be used.

20 [0066] <(B) Aromatic maleimide compound>

The resin composition of the present embodiment may comprise a (B) aromatic maleimide compound. The (B) aromatic maleimide compound according to the present embodiment is referred to as a (B)

component in some cases. The (B) component is a maleimide compound different from the (A) component. Here, a compound capable of corresponding to both of the (A) component and the (B) component is determined to belong to an (A) component, but in the case of containing two or more compounds capable of corresponding to both of the (A) component and the (B) component, one of them is determined to belong to an (A) component and the others are determined to belong to (B) components. By using the (B) component, the resin composition becomes one excellent particularly in the low thermal expansion characteristics. That is, the resin composition of the present embodiment, by using the (A) component and the (B) component in combination, can be further improved in the low thermal expansion characteristics and the like while retaining good dielectric characteristics. It is presumed that the reason therefor is because a cured substance obtained from the resin composition containing the (A) component and the (B) component contains a polymer having a structural unit consisting of the (A) component, which has low dielectric characteristics, and a structural unit consisting of the (B) component, which is low in the thermal expansion.

[0067] That is, it is preferable that the (B) component have a lower thermal expansion coefficient than the (A) component. Examples of the (B) component having a lower thermal expansion coefficient than the (A) component include maleimido group-containing compounds having a lower molecular weight than the (A) component, maleimido group-containing compounds having more aromatic rings than the (A) component, and maleimido group-containing compounds having a

shorter main chain than the (A) component.

[0068] The content of the (B) component in the resin composition is not especially limited. From the viewpoint of the low thermal expansion property and the dielectric characteristics, it is preferable that the content of the (B) component be 1 to 95% by mass to the total mass of the resin composition (solid content); being 1 to 50% by mass is more preferable; and being 1.5 to 30% by mass is still more preferable.

[0069] The blend proportion of the (A) component and the (B) component in the resin composition is not especially limited. From the viewpoint of the dielectric characteristics and the low thermal expansion coefficient, it is preferable that the mass ratio (B)/(A) of the (A) component and the (B) component be 0.01 to 3; being 0.03 to 2 is more preferable; being 0.05 to 1 is still more preferable; and being 0.05 to 0.5 is especially preferable.

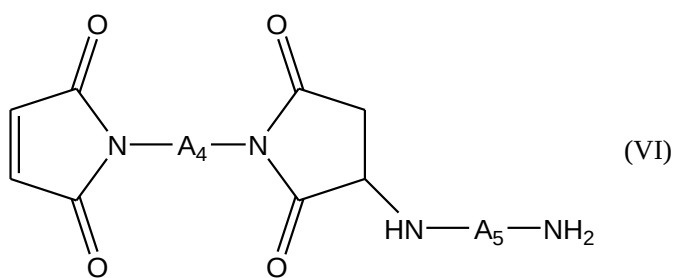
[0070] The (B) component is not especially limited as long as having an aromatic ring. Since the aromatic ring is rigid and low in the thermal expansion, by using the (B) component having an aromatic ring, the thermal expansion coefficient of the resin composition can be reduced. Although the maleimido group may be bonded to an aromatic ring or to an aliphatic chain, from the viewpoint of the low thermal expansion property, it is preferable that the maleimido group be bonded to an aromatic ring. Further it is also preferable that the (B) component be a polymaleimide compound containing two or more maleimido groups.

[0071] Specific examples of the (B) component include 1,2-dimaleimidoethane, 1,3-dimaleimidopropane, bis(4-maleimidophenyl)methane, bis(3-ethyl-4-maleimidophenyl)methane,

bis(3-ethyl-5-methyl-4-maleimidophenyl)methane, 2,7-
 dimaleimidofluorene, N,N'-(1,3-phenylene)bismaleimide, N,N'-(1,3-(4-
 methylphenylene))bismaleimide, bis(4-maleimidophenyl) sulfone, bis(4-
 maleimidophenyl) sulfide, bis(4-maleimidophenyl) ether, 1,3-bis(3-
 5 maleimidophenoxy)benzene, 1,3-bis(3-(3-
 maleimidophenoxy)phenoxy)benzene, bis(4-maleimidophenyl) ketone,
 2,2-bis(4-(4-maleimidophenoxy)phenyl)propane, bis(4-(4-
 maleimidophenoxy)phenyl) sulfone, bis[4-(4-
 maleimidophenoxy)phenyl] sulfoxide, 4,4'-bis(3-
 10 maleimidophenoxy)biphenyl, and 1,3-bis(2-(3-
 maleimidophenyl)propyl)benzene. These may be used singly or in
 combinations of two or more. Among these, from the viewpoint of
 more reducing the hygroscopic property and the thermal expansion
 coefficient, it is preferable to use bis(3-ethyl-5-methyl-4-
 15 maleimidophenyl)methane. From the viewpoint of further enhancing
 the breaking strength of a resin film formed from the resin composition
 and the metal foil peel strength, as the (B) component, it is preferable to
 use 2,2-bis(4-(4-maleimidophenoxy)phenyl)propane.

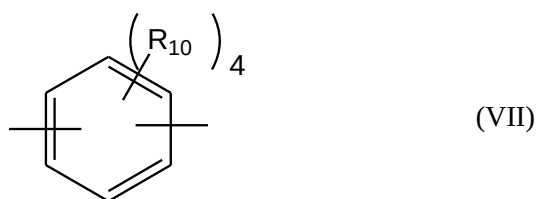
[0072] From the viewpoint of the moldability, it is preferable that the (B)
 20 component be, for example, a compound represented by the following
 formula (VI).

[0073] [Chemical Formula 18]



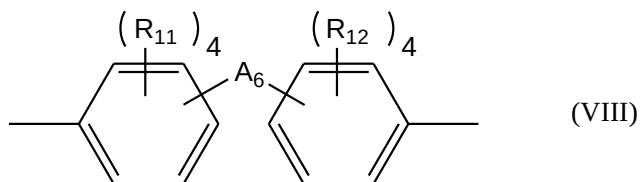
[0074] In the formula (VI), A_4 represents a residue represented by the following formula (VII), (VIII), (IX) or (X); and A_5 represents a residue represented by the following formula (XI). From the viewpoint of the low thermal expansion property, it is preferable that A_4 be a residue represented by the following formula (VII), (VIII) or (IX).

[0075] [Chemical Formula 19]



[0076] In the formula (VII), R_{10} each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom.

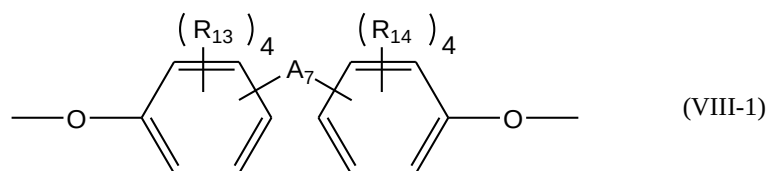
[0077] [Chemical Formula 20]



[0078] In the formula (VIII), R_{11} and R_{12} each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom; and A_6 represents an alkylene group or an alkylidene group having 1 to 5 carbon atoms, an ether group, a sulfide

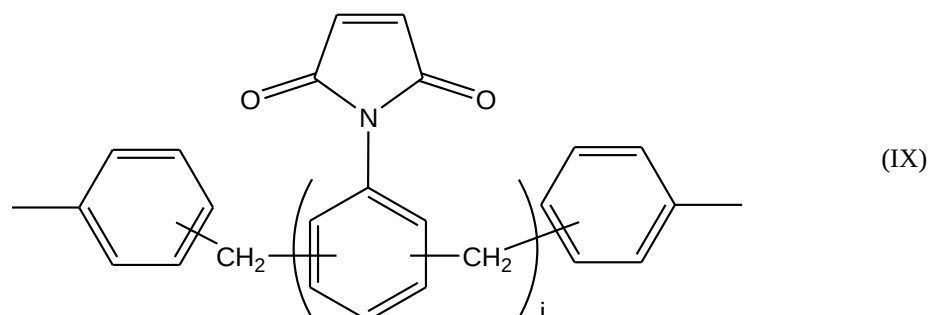
group, a sulfonyl group, a carbonyl group, a single bond or a residue represented by the following formula (VIII-1).

[0079] [Chemical Formula 21]



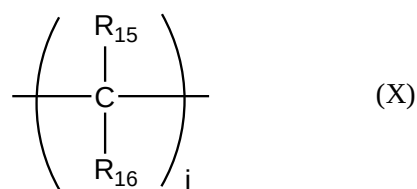
5 [0080] In the formula (VIII-1), R_{13} and R_{14} each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom; and A_7 represents an alkylene group having 1 to 5 carbon atoms, an isopropylidene group, an ether group, a sulfide group, a sulfonyl group, a carbonyl group or a single bond.

10 [0081] [Chemical Formula 22]



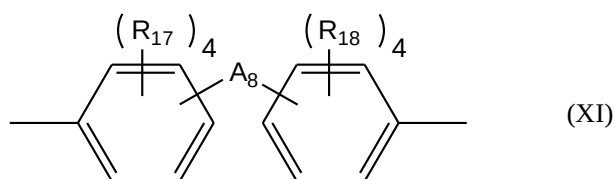
[0082] In the formula (IX), i is an integer of 1 to 10.

[0083] [Chemical Formula 23]



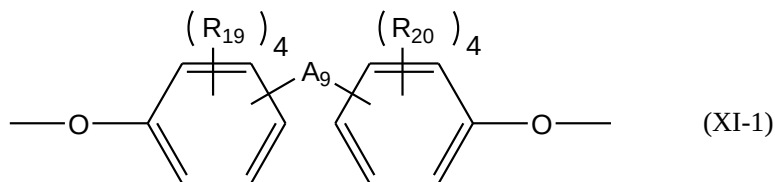
15 [0084] In the formula (X), R_{15} and R_{16} each independently represent a hydrogen atom or an aliphatic hydrocarbon group having 1 to 5 carbon atoms; and j is an integer of 1 to 8.

[0085] [Chemical Formula 24]



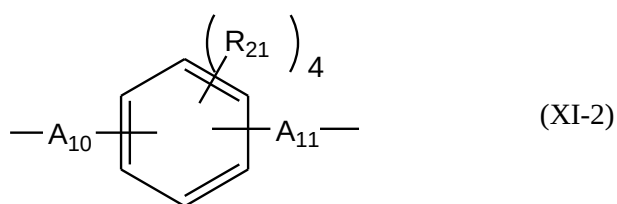
[0086] In the formula (XI), R₁₇ and R₁₈ each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an alkoxy group having 1 to 5 carbon atoms, a hydroxyl group or a halogen atom; and A₈ represents an alkylene group or an alkylidene group having 1 to 5 carbon atoms, an ether group, a sulfide group, a sulfonyl group, a carbonyl group, a fluorenylene group, a single bond, a residue represented by the following formula (XI-1) or a residue represented by the following formula (XI-2).

[0087] [Chemical Formula 25]



[0088] In the formula (XI-1), R₁₉ and R₂₀ each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom; and A₉ represents an alkylene group having 1 to 5 carbon atoms, an isopropylidene group, a m-phenylenediisopropylidene group, a p-phenylenediisopropylidene group, an ether group, a sulfide group, a sulfonyl group, a carbonyl group or a single bond.

[0089] [Chemical Formula 26]



[0090] In the formula (XI-2), R_{21} each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom; and A_{10} and A_{11} each independently represent an alkylene group having 1 to 5 carbon atoms, an isopropylidene group, an ether group, a sulfide group, a sulfonyl group, a carbonyl group or a single bond.

[0091] (Diamine compound)

The resin composition according to the present embodiment may further comprise a diamine compound. The diamine compound is not especially limited, but examples thereof include 4,4'-diaminodiphenylmethane, 4,4'-diamino-3,3'-dimethyl-diphenylmethane, 2,2'-dimethyl-4,4'-diaminobiphenyl, 2,2-bis(4-(4-aminophenoxy)phenyl)propane, 4,4'-[1,3-phenylenebis(1-methylethylidene)]bis-aniline, 4,4'-[1,4-phenylenebis(1-methylethylidene)]bis-aniline, and 1,3-bis[2-(4-aminophenyl)-2-propyl]benzene. These may be used singly or in combinations of two or more.

[0092] Further from the viewpoint of the solubility to organic solvents being high, the reaction ratio in the synthesis being high, and the heat resistance being capable of being raised, 1,3-bis[2-(4-aminophenyl)-2-propyl]benzene, 4,4'-diaminodiphenylmethane or 4,4'-diamino-3,3'-dimethyl-diphenylmethane are preferable. These may be used singly or

in combinations of two or more according to the purposes, applications and the like.

[0093] (Catalyst)

The resin composition according to the present embodiment may further comprise a catalyst to promote curing of the (A) component. The content of the catalyst is not especially limited, but may be 0.1 to 5% by mass to the total mass of the resin composition. As the catalyst, there can be used, for example, peroxides and azo compounds.

[0094] Examples of the peroxide include dicumyl peroxide, dibenzoyl peroxide, 2-butanone peroxide, tert-butyl perbenzoate, di-tert-butyl peroxide, 2,5-dimethyl-2,5-di(t-butylperoxy)hexane, bis(tert-butylperoxyisopropyl)benzene and tert-butyl hydroperoxide. Examples of the azo compound include 2,2'-azobis(2-methylpropanenitrile), 2,2'-azobis(2-methylbutanenitrile) and 1,1'-azobis(cyclohexanecarbonitrile).

[0095] (Thermoplastic resin)

The resin composition of the present embodiment comprises a thermoplastic resin from the viewpoint of enhancing the handleability of the resin film. The kind of the thermoplastic resin is not especially limited, and the molecular weight also is not limited, but from the viewpoint of enhancing the compatibility with the (A) component, it is preferable that the number-average molecular weight (M_n) be 200 to 60000.

[0096] From the viewpoint of the film formability and the hygroscopic resistance, it is preferable that the thermoplastic resin be a thermoplastic elastomer. Examples of the thermoplastic elastomer include styrene-based elastomer, olefin-based elastomer, urethane-based elastomer,

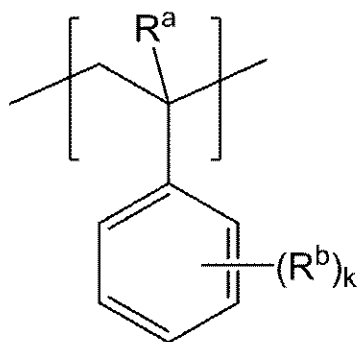
polyester-based elastomer, polyamide-based elastomer, acrylic elastomer, silicone-based elastomer and derivatives thereof. The thermoplastic resin may be used singly or as a mixture of two or more.

[0097] Then as the thermoplastic elastomer, there can be used one having a reactive functional group on its molecular terminal or in its molecular chain. Examples of the reactive functional group include an epoxy group, a hydroxyl group, a carboxy group, an amino group, an amido group, an isocyanate group, an acryloyl group, a methacryloyl group and a vinyl group. Making these reactive functional groups to be incorporated on molecular terminals or in molecular chains improves the compatibility and enables the internal stress generated during curing of a thermosetting resin composition to be more effectively reduced and the warping of substrates to be reduced.

Among these reactive functional groups, it is preferable that the thermoplastic elastomer have an epoxy group, a hydroxy group, a carboxy group, an amino group or an amido group from the viewpoint of the close adhesiveness to metal foils; and it is more preferable that the thermoplastic elastomer have an epoxy group, a hydroxy group or an amino group from the viewpoint of the heat resistance and the insulation reliability.

[0098] The styrene-based elastomer is not especially limited as long as being a thermoplastic elastomer having a structural unit (see the following formula) originated from a styrene-based compound represented by the following formula, and may be a thermoplastic elastomer having a structural unit (R^a is a hydrogen atom, k is 0) originated from styrene.

[Chemical Formula 27]



(structural unit originated from a styrene-based compound)

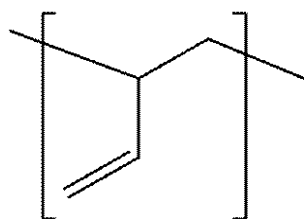
[0099] In the above formula, R^a is a hydrogen atom or an alkyl group having 1 to 5 carbon atoms; R^b is an alkyl group having 1 to 5 carbon atoms; and k is an integer of 0 to 5. Examples of the alkyl group having 1 to 5 carbon atoms represented by R^a and R^b include a methyl group, an ethyl group and an n-propyl group. R^a and R^b may also be an alkyl group having 1 to 3 carbon atoms, and may also be a methyl group. R^a may also be a hydrogen atom. k may be an integer of 0 to 2, may also be 0 or 1 or may also be 0.

[0100] The styrene-based elastomer may be at least one selected from a hydrogenated substance of styrene-butadiene-styrene block copolymers (SEBS, SBBS), a hydrogenated substance of styrene-isoprene-styrene block copolymers (SEPS) and styrene-maleic anhydride copolymers (SMA) from the viewpoint of the high-frequency characteristics (low dielectric constant, low dielectric loss tangent), the adhesiveness to conductors, the heat resistance, the glass transition temperature and the thermal expansion coefficient.

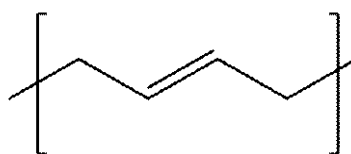
[0101] The hydrogenated substance of styrene-butadiene-styrene block copolymers come in SEBS, in which the hydrogenation rate of carbon-

carbon double bonds is usually 90% or higher (may be 95% or higher), and SBBS (the hydrogenation rate of whole carbon-carbon double bonds is about 60 to 85%), in which carbon-carbon double bonds (see the following left formula) at 1,2-bonding sites in the butadiene block are partially hydrogenated.

[Chemical Formula 28]



carbon-carbon double bond
at a 1,2-bonding site



carbon-carbon double bond
at a 1,4-bonding site

[0102] The content ratio (hereinafter, abbreviated to styrene content ratio in some cases) of a structural unit originated from styrene in SEBS, from the viewpoint of the high-frequency characteristics (low dielectric constant, low dielectric loss tangent), the adhesiveness to conductors, the heat resistance, the glass transition temperature and the thermal expansion coefficient, may be 5 to 80% by mass, may also be 5 to 70% by mass, may also be 10 to 70% by mass, or may also be 10 to 50% by mass. The melt flow rate (MFR) of SEBS is not especially limited, and under the measurement condition of 230°C and a load of 2.16 kgf (21.2 N), may be 0.1 to 20 g/10 min, or may also be 0.5 to 15 g/10 min.

[0103] The styrene content ratio in SBBS, from the viewpoint of the high-frequency characteristics (low dielectric constant, low dielectric loss tangent), the adhesiveness to conductors, the heat resistance, the glass

transition temperature and the thermal expansion coefficient, may be 40 to 80% by mass, may also be 50 to 75% by mass, or may also be 55 to 75% by mass. The melt flow rate (MFR) of SBBS is not especially limited, and under the measurement condition of 190°C and a load of 2.16 kgf (21.2 N), may be 0.1 to 10 g/10 min, may also be 0.5 to 10 g/10 min, or may also be 1 to 6 g/10 min.

[0104] The hydrogenation rate of the hydrogenated substance of styrene-isoprene-styrene block copolymer (SEPS) may be 90% or higher, or may also be 95% or higher. The styrene content ratio in SEPS, from the viewpoint of the high-frequency characteristics (low dielectric constant, low dielectric loss tangent), the adhesiveness to conductors, the heat resistance, the glass transition temperature and the thermal expansion coefficient, may be 5 to 60% by mass, may also be 5 to 50% by mass, or may also be 10 to 40% by mass. The melt flow rate (MFR) of SEPS is not especially limited, and under the measurement condition of 230°C and a load of 2.16 kgf (21.2 N), may be 0.1 to 130 g/10 min, may also be 10 to 100 g/10 min, or may also be 50 to 90 g/10 min.

[0105] Examples of the olefin-based elastomer include copolymers of α -olefins having 2 to 20 carbon atoms such as ethylene, propylene, 1-butene, 1-hexene and 4-methyl-1-pentene; copolymers of α -olefins with nonconjugated dienes having 2 to 20 carbon atoms such as dicyclopentadiene, 1,4-hexadiene, cyclooctadiene, methylene norbornene, ethylidene norbornene, butadiene and isoprene.

[0106] Examples of the copolymers of α -olefins include ethylene-propylene copolymers (EPR) and ethylene-propylene-diene copolymers (EPDM).

[0107] Examples of the urethane-based elastomer include ones having a hard segment consisting of a low-molecular (short-chain) diol and a diisocyanate, and a soft segment consisting of a high-molecular (long-chain) diol and a diisocyanate.

5 [0108] Examples of the low-molecular (short-chain) diol include ethylene glycol, propylene glycol, 1,4-butanediol and bisphenol A. It is preferable that the number-average molecular weight of the low-molecular (short-chain) diol be 48 to 500. Examples of the high-molecular (long-chain) diol include polypropylene glycol,
10 polytetramethylene oxide, poly(1,4-butylene adipate), poly(ethylene-1,4-butylene adipate), polycaprolactone, poly(1,6-hexylene carbonate) and poly(1,6-hexylene-neopentylene adipate). It is preferable that the number-average molecular weight of the high-molecular (long-chain) diol be 500 to 10000.

15 [0109] Examples of the polyester-based elastomer include ones obtained by polycondensing a dicarboxylic acid or a derivative thereof with a diol compound or a derivative thereof.

[0110] Examples of the dicarboxylic acid include aromatic dicarboxylic acids such as terephthalic acid, isophthalic acid and naphthalene
20 dicarboxylic acid; and aliphatic dicarboxylic acids such as adipic acid, sebacic acid and dodecanedicarboxylic acid. The dicarboxylic acid may be used singly or as a mixture of two or more.

[0111] Examples of the diol compound include aliphatic diols, alicyclic diols and aromatic diols. The diol compound may be used singly or as
25 a mixture of two or more.

[0112] As the polyester-based elastomer, there may be used a multi-block

copolymer having an aromatic polyester (for example, polybutylene terephthalate) moiety as a hard segment component and an aliphatic polyester (for example, polytetramethylene glycol) moiety as a soft segment component.

5 [0113] Examples of the polyamide-based elastomer include block copolymers having a polyamide as a hard segment component and having a polybutadiene, butadiene-acrylonitrile copolymer, styrene-butadiene copolymer, polyisoprene, ethylene propylene copolymer, polyether, polyester, polybutadiene, polycarbonate, polyacrylate, polymethacrylate,
10 polyurethane, silicone rubber, or the like as a soft segment component.

[0114] Examples of the acrylic elastomer include polymers made by polymerizing raw material monomers containing acrylate esters as a main component. Examples of the acrylate esters include ethyl acrylate, butyl
15 acrylate, methoxyethyl acrylate and ethoxyethyl acrylate. The acrylic elastomer specifically includes acrylonitrile-butyl acrylate copolymers, acrylonitrile-butyl acrylate-ethyl acrylate copolymers and acrylonitrile-butyl acrylate-glycidyl methacrylate copolymers.

[0115] The silicone-based elastomer is, for example, an elastomer containing an organopolysiloxane as a main component, and according to
20 its skeleton structure, is classified into polydimethylsiloxane-based one, polymethylphenylsiloxane-based one, polydiphenylsiloxane-based one and the like.

[0116] Among these thermoplastic elastomers, from the viewpoint of the heat resistance and the insulation reliability, preferable are styrene-based
25 elastomer, olefin-based elastomer, polyamide-based elastomer and silicone-based elastomer; and from the viewpoint of the dielectric

characteristics, more preferable are styrene-based elastomer and olefin-based elastomer, and still more preferable is hydrogenated styrene-based thermoplastic elastomer.

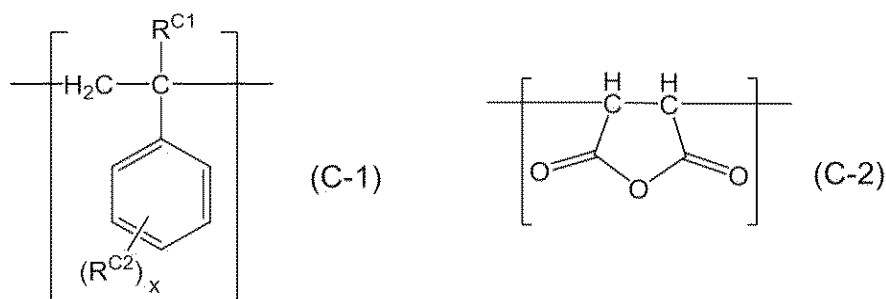
[0117] The thermoplastic elastomer may be a modified elastomer.

5 Examples of the modified elastomer include copolymer resins of an above-mentioned elastomer with an acid anhydride.

[0118] As the modified elastomer, for example, a copolymer resin (hereinafter, referred to as elastomer (x)) of a styrene-based elastomer with an acid anhydride is preferable. Examples of the elastomer (x) include modified elastomer containing a structural unit originated from an aromatic vinyl compound and a structural unit originated from maleic anhydride. As the structural unit in the elastomer (x) originated from an aromatic vinyl compound, preferable is a structural unit represented by the following formula (C-1); and as the structural unit originated from maleic anhydride, preferable is a structural unit represented by the following formula (C-2).

[0119]

[Chemical Formula 29]



20 In the formula, $\text{R}^{\text{C}1}$ represents a hydrogen atom or an aliphatic hydrocarbon group having 1 to 5 carbon atoms; $\text{R}^{\text{C}2}$ each independently represent an aliphatic hydrocarbon group having 1 to 5 carbon atoms or

an aromatic hydrocarbon group having 6 to 20 carbon atoms; and x represents an integer of 0 to 3.

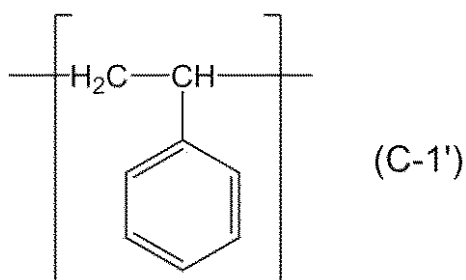
[0120] Examples of aliphatic hydrocarbon groups having 1 to 5 carbon atoms represented by R^{C1} and R^{C2} include a methyl group, an ethyl group, an n-propyl group, an isopropyl group, an n-butyl group, an isobutyl group, a t-butyl group and an n-pentyl group. Among these, from the viewpoint of the adhesiveness to copper foils and the dielectric characteristics, preferable are aliphatic hydrocarbon groups having 1 to 3 carbon atoms, and more preferable are a methyl group and an ethyl group.

Examples of aromatic hydrocarbon groups having 6 to 20 carbon atoms represented by R^{C2} include a phenyl group, a naphthyl group, an anthryl group and a biphenyl group.

[0121] In the structural unit represented by the above formula (C-1), preferable is a structural unit represented by the following formula (C-1') in which R^{C1} is a hydrogen atom and x is 0.

[0122]

[Chemical Formula 30]



[0123] It is preferable that the content ratio [(C-1)/(C-2)] of the structural unit represented by the formula (C-1) and the structural unit represented by the formula (C-2) in the elastomer (x) be 2 to 10; and being 3 to 9 is more preferable. When the content ratio is 2 or higher, the improving

effect of the dielectric characteristics and the heat resistance is likely to become sufficient; and when being 10 or lower, the compatibility is likely to become good. It is preferable that the total content of the structural unit represented by the formula (C-1) and the structural unit represented by the formula (C-2) in the elastomer (x) be 50% by mass or higher; being 70% by mass or higher is more preferable; being 90% by mass or higher is still more preferable; and being substantially 100% by mass is especially preferable.

[0124] It is preferable that the weight-average molecular weight (M_w) of the elastomer (x) be 5000 to 18000; being 6000 to 17000 is more preferable; being 8000 to 16000 is still more preferable; being 10000 to 16000 is especially preferable; and being 12000 to 16000 is most preferable. Here, any weight-average molecular weights in the present description are values measured by gel permeation chromatography (GPC) (in terms of standard polystyrene) using tetrahydrofuran as an eluate.

[0125] It is preferable that the content of the elastomer (x) in the resin composition be, with respect to 100 parts by mass of the solid content of the resin composition, 2 to 20 parts by mass; being 3 to 15 parts by mass is more preferable; and being 4 to 13 parts by mass is still more preferable. When the content of the elastomer (x) is 2 parts by mass or higher, the effect of making the dielectric constant low can be sufficiently attained; and when being 20 parts by mass or lower, the dispersibility of the elastomer (x) is excellent and the heat resistance and the peel strength are excellent.

[0126] As the reactive functional group the thermoplastic resin has on its

molecular terminal or in its molecular chain, for example, from the viewpoint of the adhesiveness to metal foils, preferable are acid anhydride groups, an epoxy group, a hydroxyl group, a carboxyl group, an amino group and amido group; from the viewpoint of the dielectric characteristics, more preferable are acid anhydride groups.

[0127] As the thermoplastic resin, resin particles can also be used. Examples of the resin particles include fluororesin-based particles and other organic microparticles.

[0128] Examples of the fluororesin-based particles include polytetrafluoroethylene (PTFE) fillers, tetrafluoroethylene-perfluoroalkyl vinyl ether copolymer (PFA) fillers, tetrafluoroethylene-hexafluoropropylene copolymer (FEP) fillers, tetrafluoroethylene-ethylene copolymer (ETFE) fillers and polychlorotrifluoroethylene (PCTFE) fillers; and among these, PTFE fillers are preferable.

[0129] Examples of the other organic microparticles include polymethyl methacrylate microparticles, polycarbonate microparticles, polystyrene microparticles, polyacryl styrene microparticles, silicone microparticles, acryl microparticles, benzoguanamine-based resin microparticles, melamine-based resin microparticles, polyolefin-based resin microparticles, polyester-based resin microparticles, polyamide resin microparticles and polyimide resin microparticles; and from the viewpoint of the dielectric characteristics, polystyrene microparticles are preferable.

[0130] The amount of the thermoplastic resin blended is not especially limited, and based on the total amount of resin components contained in the resin composition of the present embodiment, being 1 to 70% by mass

is preferable; being 5 to 60% by mass is more preferable; being 10 to 50% by mass is still more preferable; and being 15 to 45% by mass is especially preferable. By making the content of the thermoplastic resin in the above range, it is likely that the dielectric loss tangent is low; the handleability when being made into films is excellent; and no resin separation of obtained interlayer insulating layers is generated.

[0131] (Inorganic filler)

The resin composition of the present embodiment may further comprise an inorganic filler. When optional suitable inorganic fillers are contained, there can be improved the low thermal expansion characteristics, the high elastic modulus property, the heat resistance, the flame retardancy and the like of the resin composition. The inorganic filler is not especially limited, but examples thereof include silica, alumina, titanium oxide, mica, beryllia, barium titanate, potassium titanate, strontium titanate, calcium titanate, aluminum carbonate, magnesium hydroxide, aluminum hydroxide, aluminum silicate, calcium carbonate, calcium silicate, magnesium silicate, silicon nitride, boron nitride, calcined clay, talc, aluminum borate, and silicon carbide. These may be used singly or in combinations of two or more.

[0132] The shape and the particle diameter of the inorganic filler are not especially limited, and the particle diameter of the inorganic filler may be, for example, 0.01 to 20 μm or 0.1 to 10 μm . Here, the particle diameter refers to an average particle diameter, and is a particle diameter at the point corresponding to 50% in volume when a cumulative frequency distribution curve of particle diameters is determined with the total volume of the particles being taken to be 100%. The average

particle diameter can be measured by a particle size distribution analyzer using a laser diffraction scattering method, or the like.

[0133] In the case of using an inorganic filler, the use volume thereof is not especially limited, but it is preferable, for example, that the content ratio of the inorganic filler be 3 to 75% by volume with respect to the total volume of the solid content in the resin composition; and being 5 to 70% by volume is more preferable. In the case where the content ratio of the inorganic filler in the resin composition is in the above range, it becomes easy for the good curability, moldability and chemical resistance to be attained.

[0134] In the case of using an inorganic filler, for the purpose of improving the dispersibility of the inorganic filler, the close adhesiveness to organic components, and the like, as required, a coupling agent can be used concurrently. The coupling agent is not especially limited, and there can be used, for example, various types of silane coupling agents, and titanate coupling agents. These may be used singly or in combinations of two or more. The amount used of the coupling agent also is not especially limited, and may be made to be, with respect to 100 parts by mass of the inorganic filler to be used, 0.1 to 5 parts by mass or 0.5 to 3 parts by mass, for example. When the amount thereof used is in this range, decreases in various characteristics are small and it becomes easy for advantages by use of the inorganic filler to be effectively exhibited.

[0135] In the case of using a coupling agent, although the so-called integral blending system may be used in which after an inorganic filler is blended in the resin composition, the coupling agent is added, it is

preferable to use a system in which there is used an inorganic filler previously surface-treated in dry or wet with the coupling agent. By using this method, advantages of the above inorganic filler can be developed more effectively.

5 [0136] (Flame retardant)

The resin composition of the present embodiment may further be blended with a flame retardant. The flame retardant is not especially limited, but there are suitably used bromine-based flame retardants, phosphorus-based flame retardants, metal hydroxides, and the like.

10 [0137] Examples of the bromine-based flame retardant include brominated epoxy resins, bromination addition-type flame retardants and bromination reaction-type flame retardants containing an unsaturated double bond group.

15 [0138] Examples of the phosphorus-based flame retardant include aromatic phosphate esters, phosphonate esters, phosphinate esters and phosphazene compounds.

[0139] Examples of the metal hydroxide flame retardants include magnesium hydroxide and aluminum hydroxide. These flame retardants may be used singly or in combinations of two or more.

20 [0140] The resin composition of the present embodiment can be obtained by homogeneously dispersing and mixing the above-mentioned respective components; and its preparation means, conditions and the like are not especially limited. Examples of the preparation means include a method in which the respective components in predetermined amounts
25 blended are fully and homogeneously stirred and mixed by a mixer or the like, and thereafter kneaded by using a mixing roll, an extrusion machine,

a kneader, a roll, an extruder, or the like; and further, the obtained kneaded material is cooled and crushed. Here, also the kneading form is not especially limited.

[0141] The relative dielectric constant of a cured substance of the resin composition of the present embodiment is not especially limited, but from the viewpoint of being suitably used in a high-frequency band, it is preferable that the relative dielectric constant at 10 GHz be 3.6 or lower; being 3.1 or lower is more preferable; and being 3.0 or lower is still more preferable. The lower limit of the relative dielectric constant is not especially limited, but may be, for example, about 1.0. Further from the viewpoint of being suitably used in a high-frequency band, it is preferable that the dielectric loss tangent of a cured substance of the resin composition of the present embodiment be 0.004 or lower; and being 0.003 or lower is more preferable. The lower limit of the relative dielectric constant is not especially limited, but may be, for example, about 0.0001. The relative dielectric constant and the dielectric loss tangent can be measured by methods shown in the below Examples.

[0142] From the viewpoint of suppressing warpage of the laminate, it is preferable that the thermal expansion coefficient of a cured substance of the resin composition of the present embodiment be 10 to 90 ppm/°C; being 10 to 45 ppm/°C is more preferable; and being 10 to 40 ppm/°C is still more preferable. The thermal expansion coefficient can be measured according to IPC-TM-650 2.4.24.

[0143] [Resin film]

In the present embodiment, a resin film can be produced by using the above-mentioned resin composition. Here, the resin film refers to

an uncured or semicured filmy resin composition.

[0144] A production method of the resin film is not limited, but the resin film can be obtained, for example, by drying a resin layer formed by applying the resin composition on a support base material. Specifically, the resin composition is applied on a support base material by using a kiss coater, a roll coater, a comma coater or the like, and thereafter, may be dried in a heating dryer or the like, for example, at a temperature of 70 to 250°C, preferably 70 to 200°C, for 1 to 30 min, preferably 3 to 15 min. Thereby, there can be obtained the resin film in the state that the resin composition is semicured.

[0145] Here, the resin film in the state of being semicured can be heat-cured by being further heated by a heating oven, for example, at a temperature of 170 to 250°C, preferably 185 to 230°C, for 60 to 150 min.

[0146] The thickness of the resin film according to the present embodiment is not especially limited, but it is preferable that the thickness be 1 to 200 μm ; being 2 to 180 μm is more preferable; and being 3 to 150 μm is still more preferable. When the thickness of the resin film is made to be in the above range, there are easily satisfied simultaneously both the thickness reduction and the good high-frequency characteristics of a printed wiring board obtained by using the resin film according to the present embodiment.

[0147] The support base material is not especially limited, but it is preferable that the support base material be at least one selected from the group consisting of glasses, metal foils and PET films. When the resin film has the support base material, the storage property and the handleability in production use of a printed wiring board are likely to

become good. That is, the resin film according to the present embodiment can take a form of a support with a resin layer which has a resin layer containing the resin composition of the present embodiment and the support base material, and the resin layer may be peeled off the support base material when the resin film is used.

[0148] [Prepreg]

The prepreg according to the present embodiment can be obtained, for example, by coating the resin composition of the present embodiment on a fiber base material being a reinforcing base material, and drying the coated resin composition. Further the prepreg of the present embodiment may be obtained by impregnating the fiber base material with the resin composition of the present embodiment, and thereafter drying the impregnated resin composition. Specifically, the prepreg in which the resin composition is semicured is obtained by drying the fiber base material on which the resin composition adheres in a drying oven usually at a temperature of 80 to 200°C for 1 to 30 min. With respect to the amount of the resin composition adhering on the fiber base material, from the viewpoint of the good moldability, it is preferable that the resin composition be coated or impregnated so that the resin content ratio in the prepreg after the drying becomes 30 to 90% by mass.

[0149] The reinforcing base material of the prepreg is not limited, and a sheet-form fiber base material is preferable. Examples of the sheet-form fiber base material include inorganic fibers of E glass, NE glass, S glass, Q glass or the like; and organic fibers of polyimide, polyester, tetrafluoroethylene or the like. As the sheet-form fiber base material, there can be used ones having a shape of woven fabric, nonwoven fabric,

chopped strand mat or the like.

[0150] [Laminate]

According to the present embodiment, there can be provided a laminate having a resin layer containing a cured substance of the above-mentioned resin composition, and a conductor layer. For example, a metal-clad laminate can be produced by using the resin film or the prepreg.

[0151] A production method of the metal-clad laminate is not limited, but a metal-clad laminate having a metal foil on at least one surface of the resin layer or the prepreg to become an insulating layer can be obtained, for example, by disposing the metal foil to become a conductor layer on at least one surface of one sheet or a plurality of stacked sheets of the resin film or the prepreg according to the present embodiment, and heating and pressing the resultant, for example, at a temperature of 170 to 250°C, preferably 185 to 230°C, and at a pressure of 0.5 to 5.0 MPa for 60 to 150 min. The heating and pressing can be carried out, for example, under the condition of a degree of vacuum of 10 kPa or lower, preferably 5 kPa or lower, and from the viewpoint of enhancing the efficiency, it is preferable that the heating and pressing be carried out in vacuum. It is preferable that the heating and pressing be carried out for 30 min from the starting time to until the molding-finishing time therefrom.

[0152] [Multilayer printed wiring board]

According to the present embodiment, there can be provided a multilayer printed wiring board having a resin layer containing a cured substance of the above-mentioned resin composition, and circuit layers.

The upper limit value of the number of circuit layers is not especially limited, and may be 3 layers to 20 layers. A multilayer printed wiring board can also be produced, for example, by using the above-mentioned resin film, prepreg or metal-clad laminate.

5 [0153] A production method of a multilayer printed wiring board is not especially limited, but a multilayer printed wiring board can be produced, for example, by first disposing the resin film on one surface or both surfaces of a core substrate having been subjected to a circuit formation processing or disposing the resin film between a plurality of core
10 substrates, subjecting the resultant to pressing and heating lamination molding or pressing and heating press molding to adhere the each layer, and thereafter subjecting the resultant to a circuit formation processing by laser boring processing, drill boring processing, metal plating processing, metal etching processing or the like. In the case where the
15 resin film has a support base material, the support base material can be peeled off in advance before the resin film is disposed on a core substrate or between core substrates, or be peeled off after the resin layer is laminated on the core substrate.

[0154] A production method of a multilayer printed wiring board using
20 the resin film according to the present embodiment will be described by way of Figure 1. Figure 1 is a diagram schematically illustrating production steps of the multilayer printed wiring board according to the present embodiment. The production method of the multilayer printed wiring board according to the present embodiment comprises (a) a step
25 (hereinafter, referred to as "step (a)") of laminating a resin film on an inner layer circuit board to form a resin layer, (b) a step (hereinafter,

referred to as "step (b)") of heating and pressing the resin layer to cure the resin layer, and (c) a step (hereinafter, referred to as "step (c)") of forming an antenna circuit layer on the cured resin layer.

[0155] As illustrated in (a) of Figure 1, a resin film 12 according to the present embodiment is laminated on an inner layer circuit board 11 to thereby form a resin layer consisting of the resin film 12 in the step (a).

[0156] A lamination method is not especially limited, but examples thereof include a method of laminating by using a multi-daylight press, a vacuum press, an atmospheric laminator or a laminator which performs heating and pressing under vacuum, and preferable is a method using the laminator which performs heating and pressing under vacuum. Thereby, even if the inner layer circuit board 11 has fine wiring circuits on its surface, spaces between the circuits can be embedded in the resin without producing voids. The lamination condition is not especially limited, but it is preferable that the lamination be carried out at a pressure bonding temperature of 70 to 130°C and a pressure bonding pressure of 1 to 11 kgf/cm², and under reduced pressure or under vacuum. The lamination may be carried out in a batch system or a continuous system using rolls.

[0157] The inner layer circuit board 11 can use, without being especially limited, a glass epoxy substrate, a metal substrate, a polyester substrate, a polyimide substrate, a BT resin substrate, a thermosetting polyphenylene ether substrate, or the like. The circuit surface on the surface side of the inner layer circuit board 11 on which the resin film is to be laminated may be previously subjected to a roughening treatment.

[0158] The number of circuit layers of the inner layer circuit board 11 is

not limited. Figure 1 illustrates an inner layer circuit board having 6 layers, but the number thereof is not limited to this number of layers; for example, in the case of fabricating a printed wiring board for a millimeter-wave radar, the number thereof can optionally be selected from 2 layers to 20 layers or so according to the design concerned. The multilayer printed wiring board of the present embodiment can be applied to fabrication of a millimeter-wave radar. That is, there can be fabricated a printed wiring board for a millimeter-wave radar which has a resin layer containing a cured substance of the resin film according to the present embodiment, and a circuit layer.

[0159] In the case where an antenna circuit layer 14 described later is formed on a resin layer 12a by etching, a metal foil 13 may further be laminated on the resin film 12 to form a metal layer 13a. Examples of the metal foil include copper, aluminum, nickel and zinc, and from the viewpoint of the conductivity, copper is preferable. The metal foil may be an alloy, and examples of copper alloys include high-purity copper alloys in which a small amount of beryllium or cadmium is added. It is preferable that the thickness of the metal foil be 3 to 200 μm ; and being 5 to 70 μm is more preferable.

[0160] As illustrated in (b) of Figure 1, the inner layer circuit board 11 and the resin layer 12a laminated in the step (a) are heated and pressed to be heat-cured in the step (b). The condition is not especially limited, but it is preferable that the condition be in the ranges of a temperature of 100°C to 250°C, a pressure of 0.2 to 10 MPa and a time of 30 to 120 min; and being 150°C to 220°C is more preferable.

[0161] As illustrated in (c) of Figure 1(c), the antenna circuit layer 14 is

formed on the resin layer 12a in the step (c). A formation method of the antenna circuit layer 14 is not especially limited, and the antenna circuit layer 14 may be formed, for example, by an etching process such as a subtractive process or a semi-additive process.

5 [0162] The subtractive process is a process of forming a desired circuit by forming an etching resist layer having a shape corresponding to a desired pattern shape on the metal layer 13a, and in a developing process thereafter, dissolving and removing the metal layer in portions where the resist is removed by using a chemical. For example, a copper chloride
10 solution or an iron chloride solution can be used as the chemical.

[0163] The semi-additive process is a process of forming a desired circuit layer by forming a metal film on the surface of the resin layer 12a by an electroless plating method, forming a plating resist layer having a shape
15 corresponding to a desired pattern on the metal film, then forming a metal layer by an electroplating method, and thereafter removing an unnecessary electrolessly plated layer by using a chemical or the like.

[0164] Further in the resin layer 12a, as required, holes such as a via hole
20 15 may be formed. A formation method of the hole is not limited, but there can be applied an NC drill, a carbon dioxide laser, a UV laser, a YAG laser, a plasma or the like.

[0165] Here, the inner layer circuit board 11 may also be produced by steps (p) to (r) illustrated in Figure 2. Figure 2 is a diagram schematically illustrating production steps of an inner layer circuit board. That is, the production method of the multilayer printed wiring board
25 according to the present embodiment may comprise a step (p), a step (q), a step (r), the step (a), the step (b) and the step (c). Hereinafter, the steps

(p) to (r) will be described.

[0166] First, as illustrated in (p) of Figure 2, core substrates 41 and prepregs 42 are laminated in the step (p). As the core substrate, there can be used, for example, a glass epoxy substrate, a metal substrate, a polyester substrate, a polyimide substrate, a BT resin substrate, or a thermosetting polyphenylene ether substrate. As the prepreg, there can be used, for example, "GWA-900G", "GWA-910G", "GHA-679G", "GHA-679G(S)", "GZA-71G" or "GEA-75G" (all, trade names), manufactured by Hitachi Chemical Co., Ltd.

[0167] Next, as illustrated in (q) of Figure 2, a laminated body obtained in the step (p) of the core substrates 41 and the prepregs 42 is heated and pressed in the step (q). The heating temperature is not especially limited, but it is preferable to be 120 to 230°C; and being 150 to 210°C is more preferable. Further the pressing pressure is not especially limited, but it is preferable to be 1 to 5 MPa; and being 2 to 4 MPa is more preferable. The heating time is not especially limited, but it is preferable to be 30 to 120 min. Thereby, there can be obtained an inner layer circuit board excellent in the dielectric characteristics, and the mechanical and electrical connection reliability in a high-temperature high-humidity.

[0168] Further as illustrated in (r) of Figure 2, as required, a through hole 43 is formed in the inner layer circuit board in the step (r). A formation method of the through hole 43 is not especially limited, and may be the same as the above-mentioned step of forming the antenna circuit layer, or may use a known method.

[0169] By the above steps, there can be produced the multilayer printed wiring board of the present embodiment. The steps (a) to (c) may

further be repeated by using the printed wiring board produced in the above steps as an inner layer circuit board.

[0170] Figure 3 is a diagram schematically illustrating production steps, of a multilayer printed wiring board, using the multilayer printed wiring board produced by the steps illustrated in Figure 1 as an inner layer circuit board. Figure 3(a), Figure 3(b) and Figure 3(c) correspond to Figure 1(a), Figure 1(b) and Figure 1(c), respectively.

[0171] Specifically, (a) of Figure 3 illustrates a step of laminating a resin film 22 on an inner layer circuit board 21 to form a resin layer 22a, and as required, laminating a metal foil 23 on the resin film 22 to form a metal layer 23a. (b) of Figure 3 illustrates a step of heating and pressing the resin layer 22a to cure the resin layer 22a; and (c) of Figure 3 illustrates a step of forming an antenna circuit layer 24 on the cured resin layer.

[0172] In Figure 1 and Figure 3, the number of the resin layers laminated on the inner layer circuit board for the purpose of forming an antenna circuit pattern and the like is made to be one layer or two layers, but the number thereof is not limited thereto; and the number of layers may be made to be 3 or more layers according to the antenna circuit design. By making an antenna circuit layer to be multilayered, it becomes easy to design antennas having wideband characteristics and antennas exhibiting little angular variation (beam tiltless) in antenna radiation patterns in the use frequency band.

[0173] The production method of a multilayer printed wiring board according to the present embodiment, since forming a resin layer by using the resin film containing the (A) component and the (B) component, can fabricate a laminated body without providing an adhesive layer except for

providing the resin layer excellent in the high-frequency characteristics. Thereby, the simplification of the steps can be achieved and the effect of further improving the high-frequency characteristics can be attained.

[0174] The resin composition, the resin film, the prepreg, the laminate and the multilayer printed wiring board according to the present embodiment as described above can suitably be used for electronic devices handling high-frequency signals of 1 GHz or higher, particularly electronic devices handling high-frequency signals of 10 GHz or higher.

[0175] Hitherto, the preferred embodiments according to the present invention have been described, but are taken as examples to describe the present invention; and there is no tenor of limiting the scope of the present invention to the embodiments. The present invention can be carried out in various modes different from the above embodiments without departing from its gist.

Examples

[0176] Hereinafter, the present invention will be described in more detail based on Examples and Comparative Examples. However, the present invention is not limited to the following Examples.

[0177] [Preparation of resin compositions]

Various resin compositions were prepared according to the following procedure. The amounts (parts by mass) of each raw material used for the preparation of resin compositions of Examples 1 to 10 and Comparative Examples 1 to 2 are collectively shown in Table 1 and Table 2.

[0178] Each component indicated in Table 1 or 2 was charged in a 300-mL four-necked flask equipped with a thermometer, a reflux cooling tube

and a stirring apparatus, stirred at 25°C for 1 hour, and thereafter filtered with a #200 nylon mesh (opening: 75 μm) to thereby obtain resin compositions.

[0179] Here, the abbreviations and the like of each material in Table 1 and Table 2 are as follows.

(1) BMI-3000 [Mw: about 3000, manufactured by Designer Molecules Inc., trade name]

(2) BMI-5000 [Mw: about 5000, manufactured by Designer Molecules Inc., trade name]

(3) BMI-1000 [bis(4-maleimidophenyl)methane, manufactured by Daiwa Kasei Industrial Co., Ltd., trade name]

(4) BMI-4000 [2,2-bis(4-(4-maleimidophenoxy)phenyl)propane, manufactured by Daiwa Kasei Industrial Co., Ltd., trade name]

(5) Bisaniline M [4,4'-[1,3-phenylenebis(1-methylethylidene)]bisaniline, manufactured by Mitsui Chemicals Inc., trade name]

(6) H1041 [a hydrogenated substance of a styrene-butadiene copolymer of less than 60000 in Mn, styrene content ratio: 30%, Mn: 58000, manufactured by Asahi Kasei Corp., trade name: "Tuftec H1041"]

(7) M1913 [a carboxylic acid-modified hydrogenated styrene-butadiene copolymer resin, manufactured by Asahi Kasei Corp., trade name: "Tuftec M1913"]

(8) MP-10 [an amine-modified styrene-based thermoplastic elastomer, manufactured by Asahi Kasei Corp., trade name: "Tuftec MP-10"]

(9) EF-80 [a maleic acid-modified styrene-based elastomer, manufactured by Cray Valley Technology USA LLC, styrene content ratio: 89% by mass, trade name: "SMA EF-80"]

(10) S202A [a polymeric polyphenylene ether constituted of 2,6-dimethylphenol, manufactured by Asahi Kasei Corp., trade name: "Xyron S202A"]

5 (11) Ricon 130MA8 [weight-average molecular weight: 5400, the number of maleic anhydride groups in one molecule: 2, manufactured by Cray Valley Technology USA LLC, trade name]

(12) PTFE filler [manufactured by Asahi Glass Co., Ltd., trade name: "Fluon L170J"]

10 (13) Styrene microparticle [manufactured by Sekisui Plastics Co., Ltd., a crosslinked polystyrene SBX, average particle diameter: 1.0 μm]

(14) Perbutyl P [α,α' -bis(t-butylperoxy)diisopropylbenzene, manufactured by NOF Corp., trade name]

15 (15) A silica slurry [a spherical fused silica, surface treatment: a phenylaminosilane coupling agent (1% by mass/total solid content in the slurry), disperse medium: methyl isobutyl ketone (MIBK), solid content concentration: 70% by mass, average particle diameter: 0.5 μm , density: 2.2 g/cm^3 , manufactured by Admatex Co., Ltd.]

[0180] [Table 1]

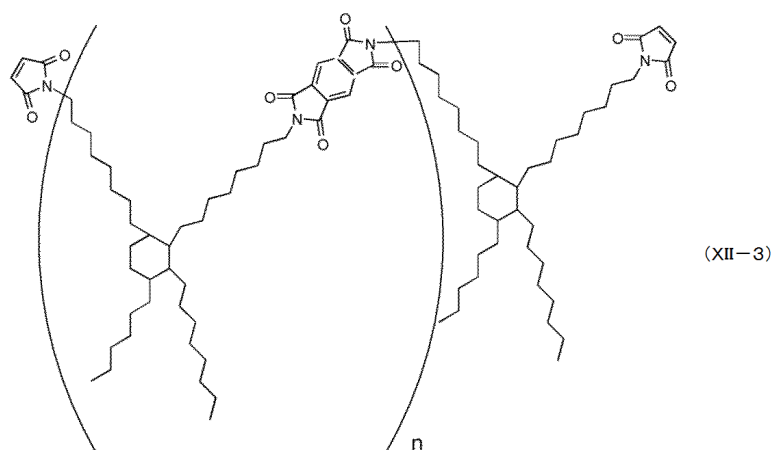
		Example									
		1	2	3	4	5	6	7	8	9	10
(A) Component	BMI-3000	80	60	80	80	80	80	80	-	72	72
	BMI-5000	-	-	-	-	-	-	-	80	-	-
(B) Component	BMI-1000	-	-	-	-	-	-	-	-	-	6
	BMI-4000	-	-	-	-	-	-	-	-	8	-
Diamine	Bisaniline M	-	-	-	-	-	-	-	-	-	2
Thermoplastic Resin	H1041	20	-	-	-	-	-	-	-	20	20
	M1913	-	40	-	-	-	-	-	-	-	-
	MP-10	-	-	20	-	-	-	-	-	-	-
	EF-80	-	-	-	20	-	-	-	-	-	-
	S202A	-	-	-	-	20	-	-	-	-	-
	Ricon130MA8	-	-	-	-	-	20	-	-	-	-
	PTFE Filler	-	-	-	-	-	-	20	-	-	-
	Styrene Microparticle	-	-	-	-	-	-	-	20	-	-
Catalyst	Perbutyl P	2.00	2.00	2.00	2.00	2.00	2.00	2.00	2.00	2.00	2.00
Silica Slurry (solid content: 70% by mass) in (), Amount of MIBK		400 (120)	400 (120)	400 (120)	400 (120)	400 (120)	400 (120)	400 (120)	400 (120)	400 (120)	400 (120)
Solvent	Toluene	43.7	43.7	43.7	43.7	43.7	43.7	43.7	43.7	43.7	43.7

[0181] [Table 2]

		Comparative Example	
		1	2
(A) Component	BMI-3000	100.0	-
	BMI-5000	-	-
(B) Component	BMI-1000	-	-
	BMI-4000	-	100.0
Catalyst	Perbutyl P	2.00	2.00
Silica Slurry (solid content: 70% by mass) in (), Amount of MIBK		400 (120)	400 (120)
Solvent	Toluene	43.7	43.7

[0182] Here, presumed structures of the compounds (BMI-3000 and BMI-5000) used as the above (A) component are as the following formula (XII-3).

[0183] [Chemical Formula 31]



[0184] [Fabrication of resin films having a resin layer in a semicured state]

The resin compositions obtained in Examples and Comparative Examples were each applied (drying temperature: 130°C) on a PET film (G2-38, manufactured by Teijin Ltd.) of 38 μm in thickness as a support base material by using a comma coater to thereby fabricate semicured resin films with a PET film, which had a resin layer in a semicured state. The thickness of the semicured resin films (resin layers) was 50 μm.

[0185] [Evaluation of the resin films]

There were evaluated the appearance and the handleability of the semicured resin films of the Examples 1 to 10 and Comparative Examples 1 to 2. The results are shown in Table 3 and Table 4.

[0186] The appearance was visually evaluated according to the following criteria.

○: there were no unevenness, no streaks and the like on the surface of the semicured resin film.

×: there were unevenness, streaks and the like on the surface of the semicured resin film, and the surface smoothness was poor.

[0187] The handleability was evaluated visually and tactually according to the following criteria.

(1) Presence/absence of tackiness on the surface at 25°C.

(2) Presence/absence of resin cracking or powder dropping when being cut by a cutter knife.

○: Both of the above (1) and (2) were absent.

×: At least either one of the above (1) and (2) was present.

[0188] [Multilayer printed wiring boards]

Multilayer printed wiring boards were fabricated by the following procedure by using the above-mentioned semicured resin films with the PET film.

A glass fabric base epoxy resin copper-clad laminate having circuit patterns formed therein was used as an inner layer circuit board; one sheet of the semicured resin film obtained by peeling the PET film off was placed on each of both surfaces of the inner layer circuit board; an electrodeposited copper foil (manufactured by Nippon Den kai, Ltd., trade name: "YGP-12") of 12 μm in thickness was disposed on each of the sheets; thereafter, end plates were placed thereon; and the resultant was subjected to heating and pressing molding under the pressing condition of 200°C/3.0 MPa/70 min to thereby fabricate a 4-layered printed wiring board.

[0189] Then, the copper foils of the outermost layers of the fabricated 4-layered printed wiring board were etched to evaluate the circuit embeddability (multilayering moldability). The multilayering moldability was visually evaluated according to the following criteria.

○: No voids nor blurs were present on the circuits.

×: Voids and blurs were present.

[0190] [Double-sided metal-clad cured resin films]

After two sheets of the resin film obtained by peeling the PET film off from the above-mentioned semicured resin film with the PET film were stacked; a low-profile copper foil (M-surface Rz: 3 μm, manufactured by Furukawa Electric Co., Ltd., trade name: "F3-WS") of 18 μm in thickness was disposed on each of both surfaces of the stacked two sheets so that the roughened surface (M-surface) contacted therewith; an end plate was placed on each of the copper foils; and the resultant was subjected to heating and pressing molding under the pressing condition of 200°C/3.0 MPa/70 min to thereby fabricate a double-sided metal-clad cured resin film (thickness: 0.1 mm).

[0191] For the above double-sided metal-clad cured resin film, there were evaluated the handleability (bending resistance), the dielectric characteristics, the copper foil peel strength, the solder heat resistance and the thermal expansion characteristics. The evaluation results are shown in Table 3 and Table 4. Methods for evaluating characteristics of the double-sided metal-clad cured resin film were as follows.

[0192] [Bending resistance]

The bending resistance was evaluated according to the following criteria by bending, by 180°, the double-sided metal-clad cured resin film whose outer layer copper foils had been etched.

○: No breaking nor cracking were generated on bending.

×: Breaking and cracking were generated on bending.

[0193] [Dielectric characteristics]

The relative dielectric constant and the dielectric loss tangent

being the dielectric characteristics were measured by a cavity resonator perturbation method, by using a test piece prepared by etching the outer layer copper foils of the double-sided metal-clad cured resin film and cutting the resultant into 60 mm in length, 2 mm in width and about 1 mm in thickness. A measuring device used was a vector network analyzer E8364B, manufactured by Agilent Technologies, Inc.; cavity resonators used were CP129 (10-GHz band resonator) and CP137 (20-GHz band resonator), manufactured by Kanto Electronics Application and Development Inc.; and the measurement program used was CPMA-V2. The condition was set at frequencies of 10 GHz and at a measurement temperature of 25°C.

[0194] [Thermal expansion coefficient (CTE)]

For the evaluation of the thermal expansion coefficient (in the film thickness direction), a test piece was prepared by etching the copper foils of both sides of the double-sided metal-clad cured resin film and cutting the resultant into 50 mm square; and the thermal expansion coefficient of the test piece was measured by a thermomechanical analyzer TMA (manufactured by TA Instruments Inc., Q400)(temperature range: 30 to 150°C, load: 5 g) according to the IPC standard (IPC-TM-650 2.4.24).

[0195] [Copper foil peel strength]

The copper foil peel strength was measured according to the standard for test methods of copper-clad laminates, JIS-C-6481. The measurement temperature was set at 25°C.

[0196] [Solder heat resistance]

For the evaluation of the solder heat resistance, test pieces were

prepared by etching the copper foil of one side of the double-sided metal-clad cured resin film and cutting the resultant into 50 mm square; the test pieces in the normal condition and test pieces having been treated for predetermined times (1, 3 and 5 hours) in a pressure cooker test (PCT) apparatus (condition: 121°C, 2.2 atm) were made to flow on a molten solder at 288°C for 20 sec; and the appearance of the cured resin films different in the treatment time was visually evaluated according to the following criteria. The evaluation was carried out by using three sheets of the test piece for the same treatment time; and the number of sheets exhibiting "○" in the following criteria is shown in Table 3 and Table 4. Here, in Table 3 and Table 4, the test piece having been treated for 1 hour is represented as PCT-1h; the test piece having been treated for 3 hours is represented as PCT-3h; and the test piece having been treated for 5 hours is represented as PCT-5h.

○: No generation of blistering or measling in the film interior and between the film and the copper foil was recognized.

×: Generation of blistering or measling in the film interior and between the film and the copper foil was observed.

[0197] [Table 3]

		Example									
		1	2	3	4	5	6	7	8	9	10
Semicured Resin Film Characteristics	Appearance	○	○	○	○	○	○	○	○	○	○
	Handleability	○	○	○	○	○	○	○	○	○	○
	Multilayering Moldability	○	○	○	○	○	○	○	○	○	○
Bending Resistance		○	○	○	○	○	○	○	○	○	○
Relative Dielectric Constant	10 GHz	2.97	2.90	2.99	2.96	2.97	2.98	2.92	2.93	3.01	3.02
Dielectric Loss Tangent	10 GHz	0.0013	0.0012	0.0014	0.0014	0.0014	0.0016	0.0013	0.0014	0.0015	0.0015
CTE (ppm/°C)		77	70	74	72	74	68	65	70	35	35
Copper Foil Peel Strength (kN/m)		0.51	0.62	0.56	0.53	0.55	0.53	0.52	0.56	0.65	0.66
Solder Heat Resistance	Normal Condition	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)
	PCT-1h	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)
	PCT-3h	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)
	PCT-5h	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)	○ (3/3)

[0198] [Table 4]

		Comparative Example	
		1	2
Semicured Resin Film Characteristics	Appearance	○	○
	Handleability	○	×
	Multilayering Moldability	○	○
Bending Resistance		○	○
Relative Dielectric Constant	10 GHz	2.95	3.12
Dielectric Loss Tangent	10 GHz	0.0015	0.0120
CTE(ppm/°C)		74	22
Copper Foil Peel Strength (kN/m)		0.42	0.62
Solder Heat Resistance	Normal Condition	○(3/3)	○(3/3)
	PCT-1h	○(3/3)	○(3/3)
	PCT-3h	○(3/3)	○(3/3)
	PCT-5h	○(3/3)	○(3/3)

[0199] As is clear from the results shown in Table 3, the semicured resin films of Examples 1 to 10 have excellent high-frequency characteristics,

adhesiveness and heat resistance.

[0200] Further a lower thermal expansion coefficient could be achieved in cases (Examples 9 to 10) where an (A) component and a (B) component were used in combination than in cases (Examples 1 to 8) where an (A) component was used singly.

Industrial Applicability

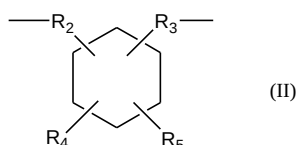
[0201] The resin composition according to the present invention is useful in applications to members and components of printed wiring boards to be used for electronic devices handling high-frequency signals of 1 GHz or higher or 10 GHz or higher, mobile communication devices and base station apparatuses thereof, network-related electronic devices such as servers and routers, and various electronic devices such as large computers since developing various characteristics and excellent high-frequency characteristics required for printed wiring boards.

Reference Signs List

[0202] 11, 21: inner layer circuit board, 12, 22: resin film, 12a, 22a: resin layer, 13, 23: metal foil, 13a, 23a: metal layer, 14, 24: antenna circuit layer, 15: via hole, 41: core substrate, 42: prepreg, and 43: through-hole.

CLAIMS

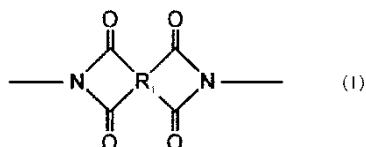
1. A resin composition comprising an (A) maleimide compound having a saturated or unsaturated divalent hydrocarbon group, and a thermoplastic resin, wherein the hydrocarbon group is a group represented by the following formula (II):



wherein in the formula (II), R₂ and R₃ each independently represent an alkylene group having 4 to 50 carbon atoms; R₄ represents an alkyl group having 4 to 50 carbon atoms; and R₅ represents an alkyl group having 2 to 50 carbon atoms,

wherein the (A) maleimide compound having a saturated or unsaturated divalent hydrocarbon group further has a divalent group having at least two imido bonds,

wherein the divalent group having at least two imido bonds is a group represented by the following formula (I):



wherein in the formula (I), R₁ represents a tetravalent organic group, and

wherein the content of the thermoplastic resin is 10 to 50% by mass based on the total amount of resin components contained in the resin

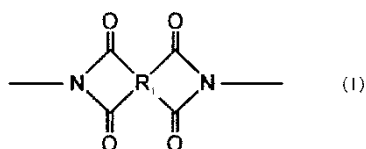
composition.

2. The resin composition according to claim 1, wherein the number of carbon atoms of the hydrocarbon group is 8 to 100.

5

3. A resin composition comprising an (A) maleimide compound having a saturated or unsaturated divalent hydrocarbon group, and a thermoplastic resin, wherein the (A) maleimide compound having a saturated or unsaturated divalent hydrocarbon group further has a divalent group having at least two imido bonds, wherein the divalent group having at least two imido bonds is a group represented by the following formula (I):

10



15

wherein in the formula (I), R_1 represents a tetravalent organic group, and wherein the content of the thermoplastic resin is 10 to 50% by mass based on the total amount of resin components contained in the resin composition.

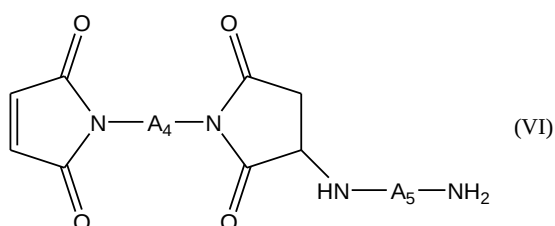
20

4. The resin composition according to claim 3, wherein the number of carbon atoms of the hydrocarbon group is 8 to 100.

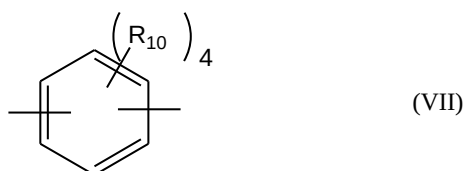
5. The resin composition according to any one of claims 1 to 4, further comprising a (B) aromatic maleimide compound having a

structure having a maleimido group bonded to an aromatic ring.

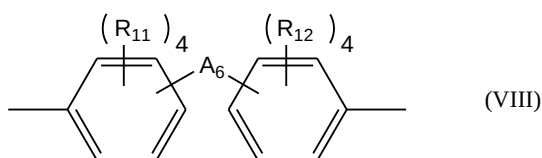
6. The resin composition according to claim 5, wherein the (B) aromatic maleimide compound is a compound represented by the following formula (VI):



wherein in the formula (VI), A_4 represents a residue represented by the following formula (VII), (VIII), (IX) or (X); and A_5 represents a residue represented by the following formula (XI):

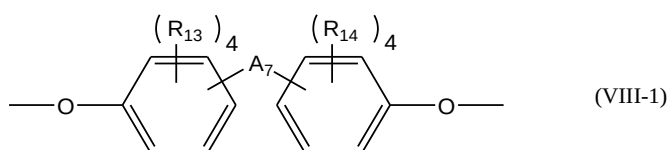


wherein in the formula (VII), R_{10} each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom,

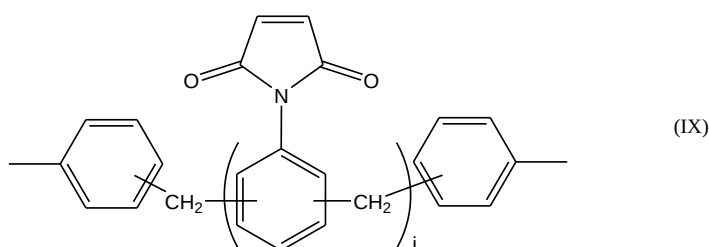


wherein in the formula (VIII), R_{11} and R_{12} each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon

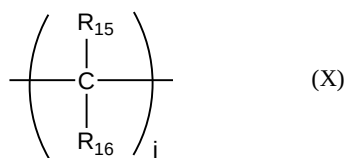
atoms or a halogen atom; and A₆ represents an alkylene group or an alkylidene group having 1 to 5 carbon atoms, an ether group, a sulfide group, a sulfonyl group, a carbonyl group, a single bond or a residue represented by the following formula (VIII-1):



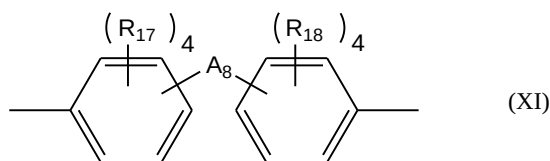
wherein in the formula (VIII-I), R₁₃ and R₁₄ each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom; and A₇ represents an alkylene group having 1 to 5 carbon atoms, an isopropylidene group, an ether group, a sulfide group, a sulfonyl group, a carbonyl group or a single bond,



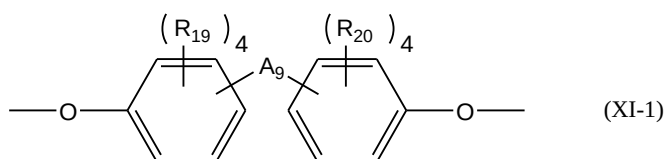
wherein in the formula (IX), i is an integer of 1 to 10,



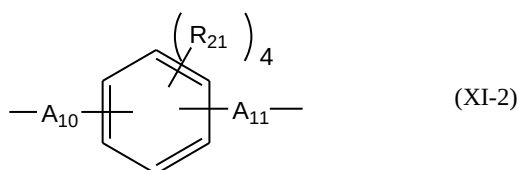
wherein in the formula (X), R₁₅ and R₁₆ each independently represent a hydrogen atom or an aliphatic hydrocarbon group having 1 to 5 carbon atoms; and j is an integer of 1 to 8,



wherein in the formula (XI), R_{17} and R_{18} each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an alkoxy group having 1 to 5 carbon atoms, a hydroxyl group or a halogen atom; and A_8 represents an alkylene group or an alkylidene group having 1 to 5 carbon atoms, an ether group, a sulfide group, a sulfonyl group, a carbonyl group, a fluorenylene group, a single bond, a residue represented by the following formula (XI-1) or a residue represented by the following formula (XI-2):



wherein in the formula (XI-I), R_{19} and R_{20} each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom; and A_9 represents an alkylene group having 1 to 5 carbon atoms, an isopropylidene group, a m-phenylenediisopropylidene group, a p-phenylenediisopropylidene group, an ether group, a sulfide group, a sulfonyl group, a carbonyl group or a single bond, and



wherein in the formula (XI-2), R_{21} each independently represent a hydrogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms or a halogen atom; and A_{10} and A_{11} each independently represent an alkylene group having 1 to 5 carbon atoms, an isopropylidene group,
5 an ether group, a sulfide group, a sulfonyl group, a carbonyl group or a single bond.

7. The resin composition according to any one of claims 1 to 6,
10 wherein a weight-average molecular weight of the (A) maleimide compound having a saturated or unsaturated divalent hydrocarbon group is 500 to 10000.

8. A laminate comprising:

a resin layer comprising a cured substance of the resin
15 composition according to any one of claims 1 to 7; and
a conductor layer.

9. A multilayer printed wiring board comprising:

a resin layer comprising a cured substance of the resin
20 composition according to any one of claims 1 to 7; and
circuit layers.